



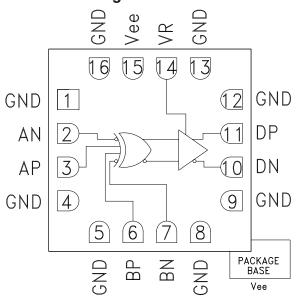
## 14 GBPS, FAST RISE TIME XOR / XNOR GATE w/ PROGRAMMABLE OUTPUT VOLTAGE

### Typical Applications

The HMC721LC3C is ideal for:

- 16 G Fiber Channel
- RF ATE Applications
- Broadband Test & Measurement
- Serial Data Transmission up to 14 Gbps
- Digital Logic Systems up to 14 GHz

### **Functional Diagram**



#### **Features**

Inputs Terminated Internally in 50 Ohms Differential or Single-Ended Operation Fast Rise and Fall Times: 19 / 18 ps Low Power Consumption: 230 mW typ. Programmable Differential Output

Voltage Swing: 600 - 1200 mVp-p Propagation Delay: 95 ps

Single Supply: -3.3 V

16 Lead Ceramic 3x3 mm SMT Package: 9 mm<sup>2</sup>

### **General Description**

The HMC721LC3C is a XOR/XNOR gate function designed to support data transmission rates of up to 14 Gbps, and clock frequencies as high as 14 GHz.

All differential inputs to the HMC721LC3C are CML and terminated on-chip with 50 Ohms to the positive supply, GND, and may be DC or AC coupled. Outputs can be connected directly to a 50 Ohm ground-terminated system or drive devices with CML logic input. The HMC721LC3C also features an ouput level control pin, VR, which allows for loss compensation or signal level optimization. The HMC721LC3C operates from a single -3.3 V supply and is available in ROHS-compliant 3x3 mm SMT package.

### Electrical Specifications, $T_A = +25$ °C, Vee = -3.3 V, VR = 0 V

Parameter	Conditions	Min.	Тур.	Max	Units
Power Supply Voltage		-3.6	-3.3	-3.0	V
Power Supply Current			70		mA
Maximum Data Rate			14		Gbps
Maximum Clock Rate			14		GHz
Input Voltage Range		-1.5		0.5	V
Input Differential Range		0.1		2.0	Vp-p
Input Return Loss	Frequency <14 GHz		10		dB
	Single-Ended, peak-to-peak		550		mVp-p
Output Amplitude	Differential, peak-to-peak		1100		mVp-p
Output High Voltage			-10		mV
Output Low Voltage			-560		mV
Output Rise / Fall Time	Differential, 20% - 80%		19 / 18		ps





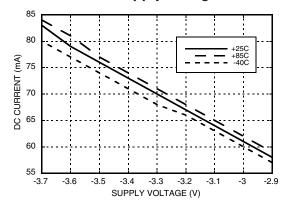
# 14 GBPS, FAST RISE TIME XOR / XNOR GATE w/ PROGRAMMABLE OUTPUT VOLTAGE

### **Electrical Specifications** (continued)

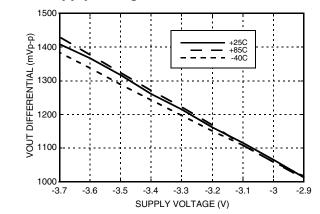
Parameter	Conditions	Min.	Тур.	Max	Units
Output Return Loss	Frequency <14 GHz		10		dB
Small Signal Gain			27		dB
Random Jitter Jr	rms			0.2	ps rms
Deterministic Jitter, Jd	peak-to-peak, 2 <sup>15</sup> -1 PRBS input <sup>[1]</sup>		2		ps, p-p
Propagation Delay, td			95		ps
VR Pin Current	VR = 0.0 V		2		mA
VR Pin Current	VR = +0.4 V			3.5	mA

<sup>[1]</sup> Deterministic jitter calculated by simultaneously measuring the jitter of a 300 mV, 13 GHz, 215-1 PRBS input, and a single-ended output

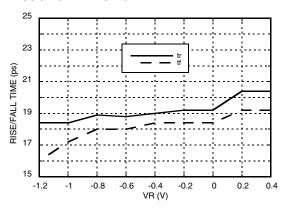
### DC Current vs. Supply Voltage [1][2]



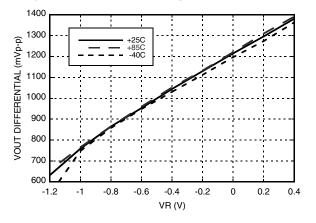
## Output Differential Voltage vs. Supply Voltage [1][3]



#### Rise / Fall Time vs. VR [2][4]



### Output Differential Voltage vs. VR [3][4]



[1] VR = 0.0 V

[2] Frequency = 13 GHz

[3] Frequency = 10 GHz

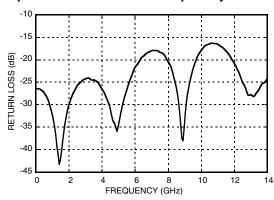
[4] Vee = -3.3 V



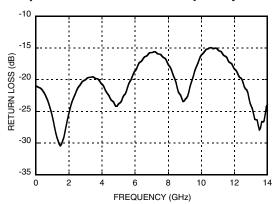


# 14 GBPS, FAST RISE TIME XOR / XNOR GATE w/ PROGRAMMABLE OUTPUT VOLTAGE

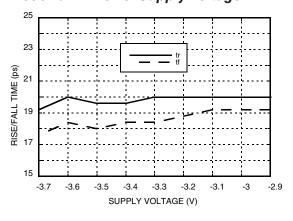
### Input Return Loss vs. Frequency



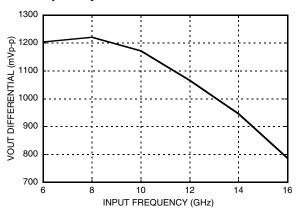
### **Output Return Loss vs. Frequency**



### Rise / Fall Time vs. Supply Voltage [1][2]



### Output Differential Voltage vs. Frequency [1][3]

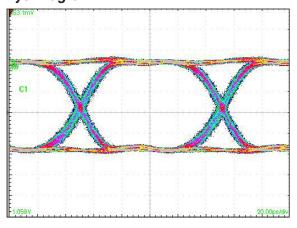






# 14 GBPS, FAST RISE TIME XOR / XNOR GATE w/ PROGRAMMABLE OUTPUT VOLTAGE

### **Eye Diagram**

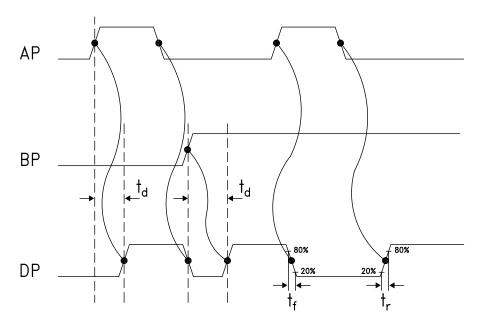


#### [1] Test Conditions:

Waveform generated with an Agilent N4903A J-Bert. Rate = 10 Gbps.

Eye diagram data presented on a Tektronix CSA 8000

### **Timing Diagram**



#### **Truth Table**

Input	Outputs	
A	В	D
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L
Notes: A = AP - AN B = BP - BN D = DP - DN	H - Positive voltage level L - Negative voltage level	





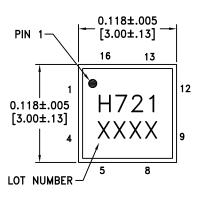
# 14 GBPS, FAST RISE TIME XOR / XNOR GATE w/ PROGRAMMABLE OUTPUT VOLTAGE

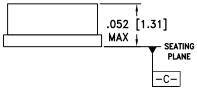
### **Absolute Maximum Ratings**

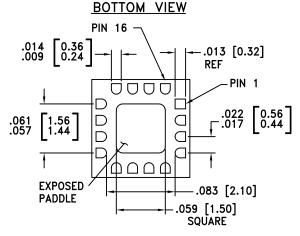
Power Supply Voltage (Vee)	-3.75 V to +0.5 V	
Input Signals	-2 V to +0.5 V	
Output Signals	-1.5 V to +1 V	
Continuous Pdiss (T = 85 °C) (derate 17 mW/°C above 85 °C)	0.68 W	
Thermal Resistance (R <sub>th j-p</sub> ) Worst case junction to package paddle	59 °C/W	
Maximum Junction Temperature	125 °C	
Storage Temperature	-65 °C to +150 °C	
Operating Temperature	-40 °C to +85 °C	
ESD Sensitivity (HBM)	Class 1C	



### **Outline Drawing**







#### NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING:
- 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05 mm DATUM -C-
- 6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
- 7. PADDLE MUST BE SOLDERED TO Vee.

### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC721LC3C	Alumina, White	Gold over Nickel	MSL3 <sup>[1]</sup>	H721 XXXX

<sup>[1]</sup> Max peak reflow temperature of 260 °C

<sup>[2] 4-</sup>Digit lot number XXXX





# 14 GBPS, FAST RISE TIME XOR / XNOR GATE w/ PROGRAMMABLE OUTPUT VOLTAGE

### **Pin Descriptions**

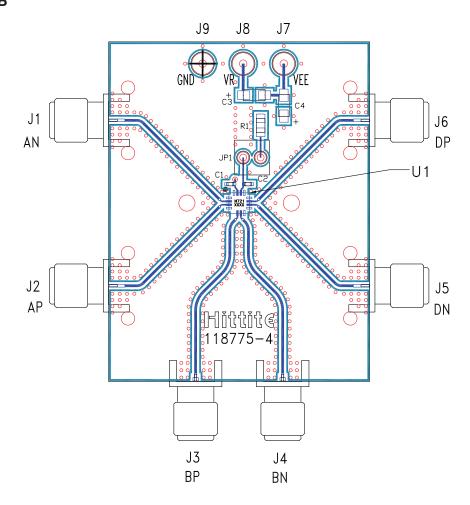
Pin Number	Function	Description	Interface Schematic
1, 4, 5, 8, 9, 12	GND	Signal Grounds	GND =
2, 3 6, 7	AN, AP BP, BN	Differential Clock / Data Inputs: Current Mode Logic (CML) referenced to positive supply	GND GND SNN
10, 11	DN, DP	Differential Clock / Data Outputs: Current Mode Logic (CML) referenced to positive supply	GND O GND  DP O O DN
13, 16	GND	Supply Ground	GND =
14	VR	Output level control. Output level may be adjusted by either applying a voltage to VR per "Output Differential vs. VR" plot.	VR 0
15, Package Base	Vee	Negative Supply	





# 14 GBPS, FAST RISE TIME XOR / XNOR GATE w/ PROGRAMMABLE OUTPUT VOLTAGE

#### **Evaluation PCB**



### List of Materials for Evaluation PCB 118777 [1]

Item	Description	
J1 - J6	PCB Mount SMA RF Connectors	
J7 - J9	DC Pin	
JP1	0.1" Header with Shorting Jumper	
C1, C2	100 pF Capacitor, 0402 Pkg.	
C3, C4	4.7 μF Capacitor, Tantalum	
R1	10 Ohm Resistor, 0603 Pkg.	
U1	HMC721LC3C High Speed Logic, XOR / XNOR	
PCB [2]	118775 Evaluation Board	

[1] Reference this number when ordering complete evaluation PCB  $\,$ 

[2] Circuit Board Material: Arlon 25FR or Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed package base should be connected to Vee. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request. Install jumper on JP1 to short VR to GND for normal operation.